



## Description

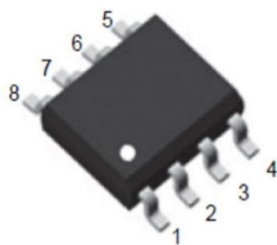
### JMT P-channel Enhancement Mode Power MOSFET

#### Features

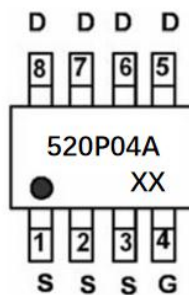
- $V_{DS} = -40V$ ,  $I_D = -5.5A$   
 $R_{DS(ON)} < 51\ m\Omega$  @  $V_{GS} = -10V$   
 $R_{DS(ON)} < 78\ m\Omega$  @  $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

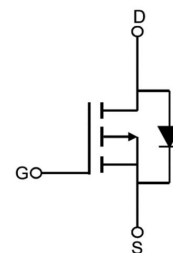
- PWM Applications
- Load Switch
- Power Management



SOP-8 top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
520P04A	JMTP520P04A	TAPING	SOP-8	13inch	4000	48000

## Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Max.	Units
$V_{DSS}$	Drain-Source Voltage	-40	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	-5.5
		$T_A = 100^\circ C$	-3.6
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	22	A
$P_D$	Power Dissipation	$T_A = 25^\circ C$	2.6
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	48	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ C$



## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> = -250μA	-40	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -40V, V <sub>GS</sub> =0V	-	-	-1	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.0	-1.6	-2.5	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance Note2	V <sub>GS</sub> = -10V, I <sub>D</sub> = -5A	-	39	51	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -4A	-	56	78	
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V, f=1.0MHz	-	869	-	pF
C <sub>oss</sub>	Output Capacitance		-	94	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	69	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -20V, I <sub>D</sub> = -4A, V <sub>GS</sub> = -10V	-	17.3	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	3.2	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	4.3	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> = -20V, I <sub>D</sub> = -4A, V <sub>GS</sub> = -10V, R <sub>GEN</sub> =3Ω	-	10.3	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	4.3	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	39	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	46.5	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	-5.5	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-22	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> = -5.5A	-	-0.8	-1.2	V
trr	Reverse Recovery Time	V <sub>GS</sub> =0V, I <sub>S</sub> = -5.5A, di/dt=100A/μs	-	17	-	ns
Qrr	Reverse Recovery Charge		-	11.5	-	nC

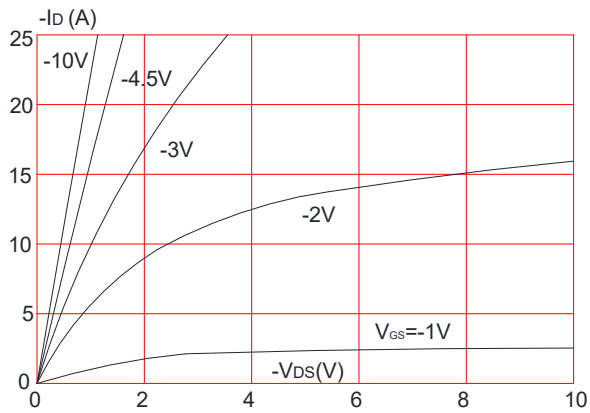
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

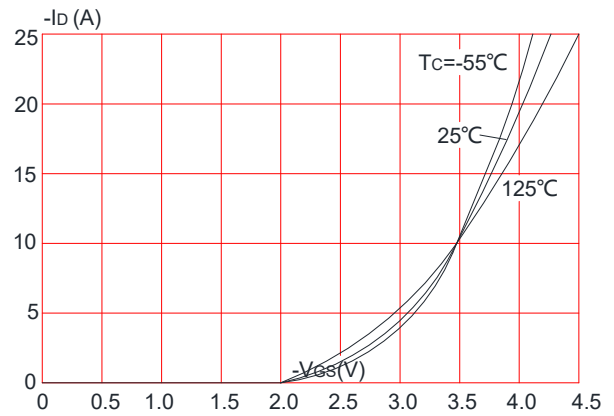


## Typical Performance Characteristics

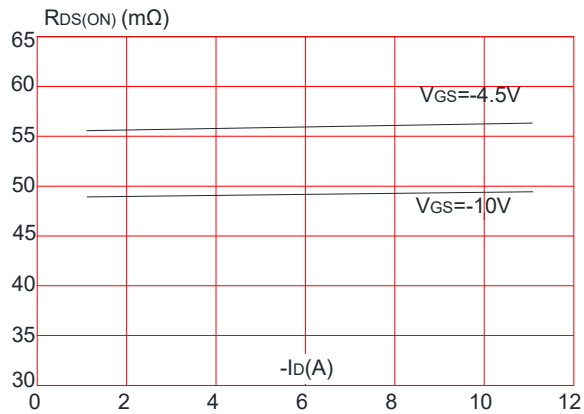
**Figure 1:** Output Characteristics



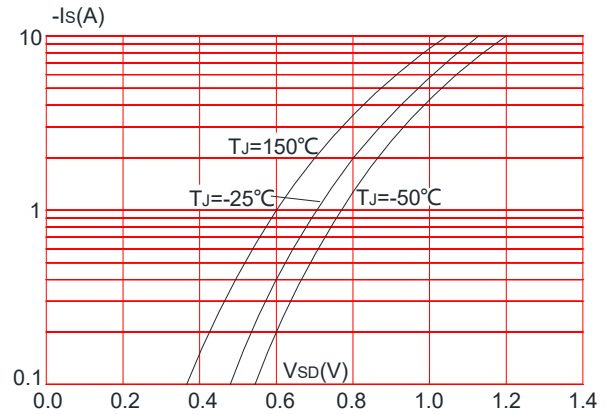
**Figure 2:** Typical Transfer Characteristics



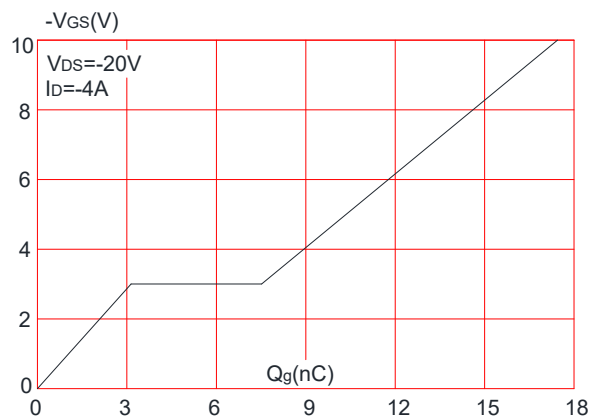
**Figure 3:** On-resistance vs. Drain Current



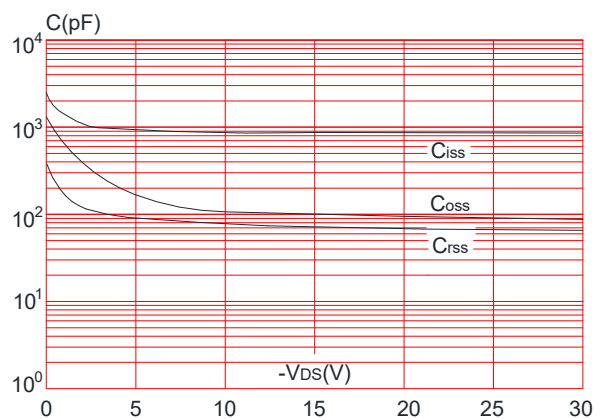
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

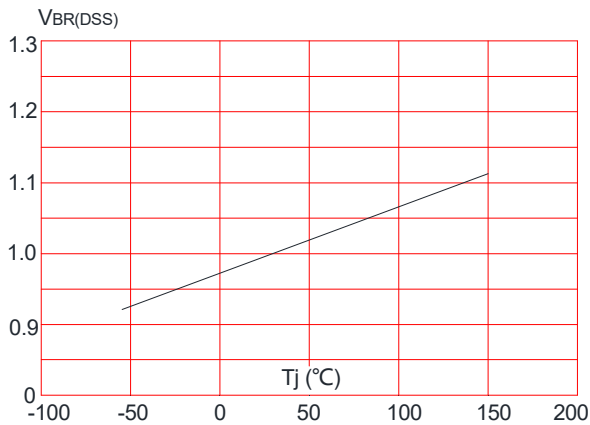


**Figure 6:** Capacitance Characteristics

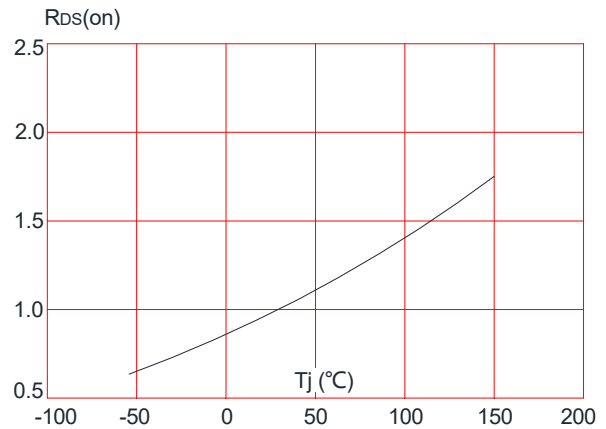




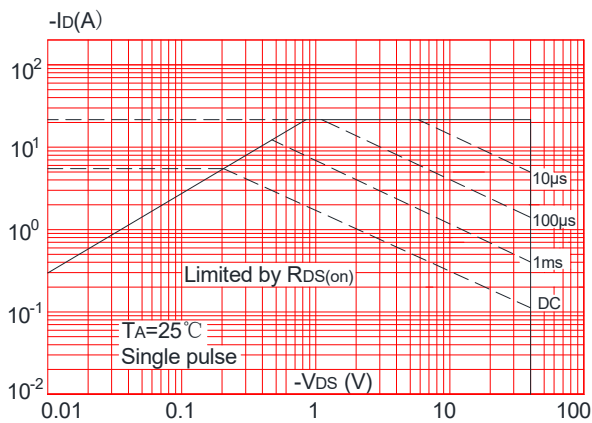
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



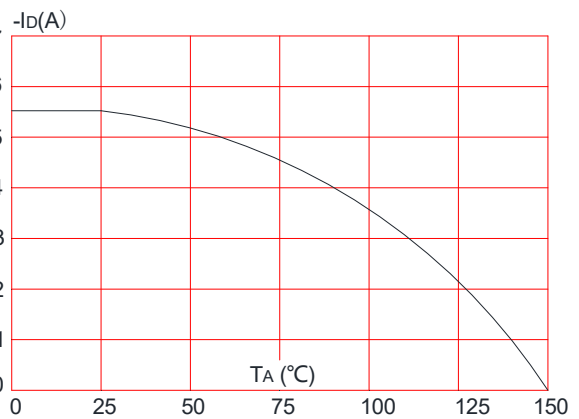
**Figure 8: Normalized on Resistance vs. Junction Temperature**



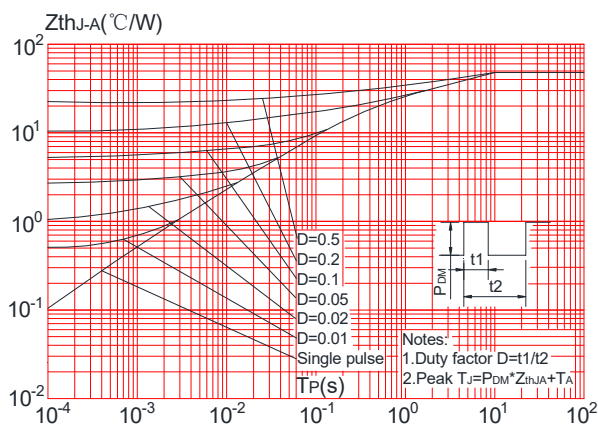
**Figure 9: Maximum Safe Operating Area**



**Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature**



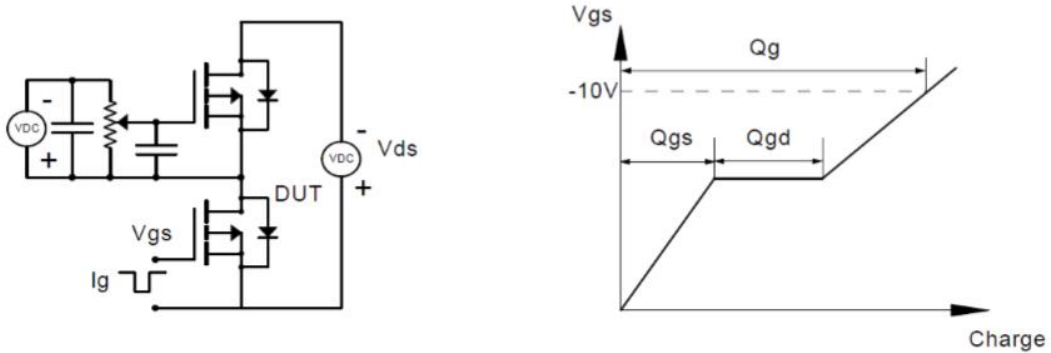
**Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**



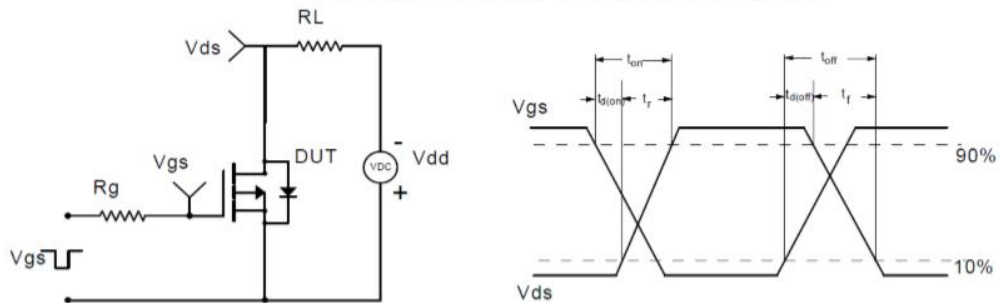


## Test Circuit

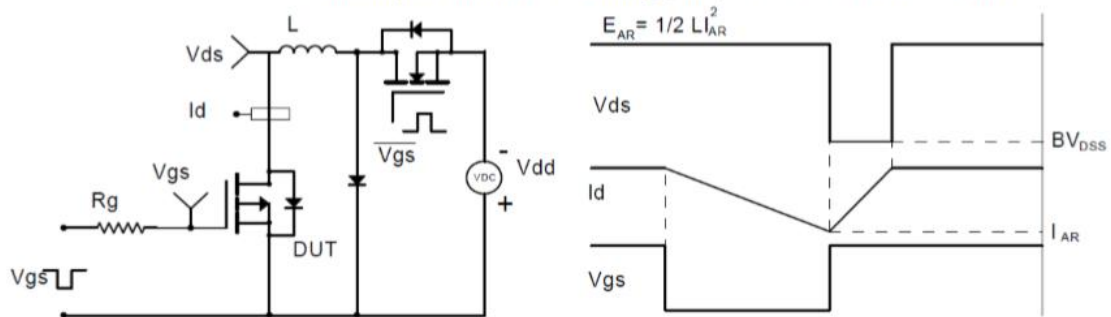
### Gate Charge Test Circuit & Waveform



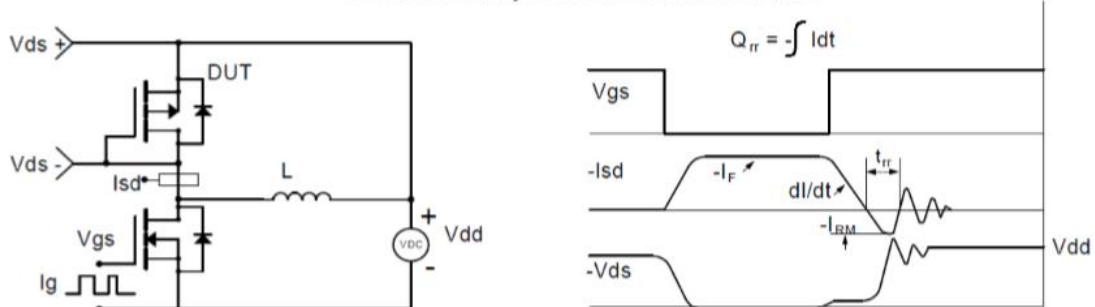
### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

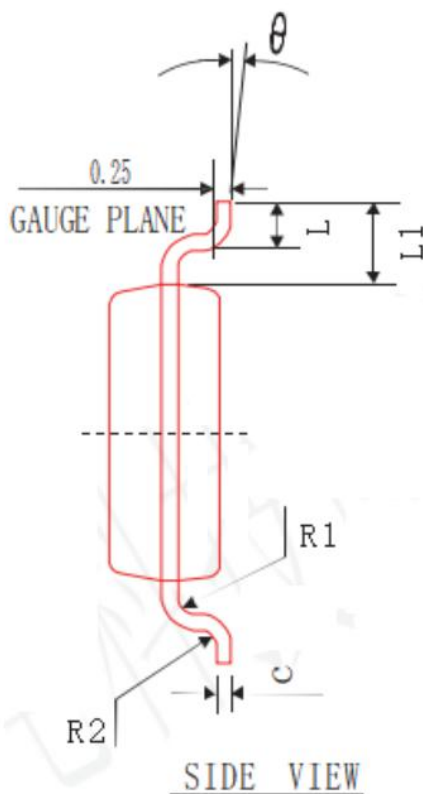
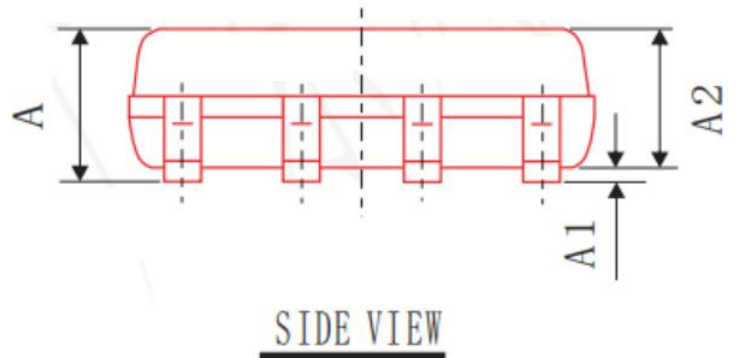
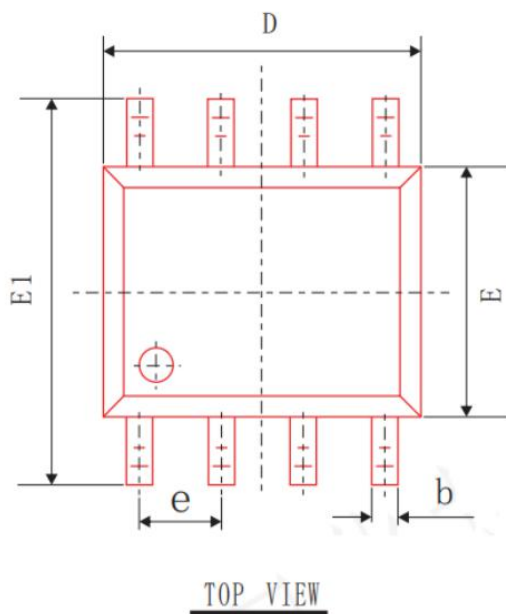


### Diode Recovery Test Circuit & Waveforms





## Package Mechanical Data-SOP-8



SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
$\theta$	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		




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